



SLOTTED SUBSTRATES AND METHODS AND SYSTEMS FOR FORMING SAME

ABSTRACT

Methods and systems for forming slots (604) in a print head substrate (606) having a thickness defined by opposing first (610) and second (612) surfaces. In one exemplary embodiment, a trench (802) is received in the first surface (610) and extends through less than an entirety of the thickness of the substrate (606). A plurality of slots (804) extends into the substrate (606) from the second surface (612) and connects with the trench (802) to form a compound slot (604) through the substrate (606). In this embodiment, the trench (802) is wider at portions proximate to said slots (804) than at portions more distant to said slots (804).

(Fig. 6)

